2024년 1월 25일(목), 10:55-12:40
Room J(204),2층

A. Interconnect & Package 분과

[TJ2-A] Advanced Packaging I

좌장: 최광성 책임(한국전자통신연구원), 여종석 교수(연세대학교)

TJ2-A-1 10:55-11:10	A Study on the Advancement of Advanced Package Process Technology Integrating Data Analytics and Machine Learning Methods Sang Yup Lee[1], Sung Hyun Yoon[2], and Je Hun Youn[2] SK hynix
TJ2-A-3 11:10-11:25	The Development of Multiple Re-distribution Layer (RDL) Using FEOL Photolithography Process for the 2.xD Packaging Applications Sun Bum Kim[1], Chan Seul Lee[1], Gyu Lee Kim[1], Sangyeun Park[2], Doheon Koo[2], Yeongu Choi[2], Joo Young Pyun[2], Chang Hoon Lee[2], Hongyun So[2], Kwan Kyu Park[2], and Changhwan Choi[1] [1]Division of Materials Science and Engineering, Hanyang University, [2]Department of Mechanical Engineering, Hanyang University
초청발표 TJ2-A-4 11:25-11:55	Low Temperature Cu-Cu Direct Bonding: A Key Technology in Advanced Semiconductor Packaging Technology Ju-Young Kim, Ji-Youn Kwak, and Youngju Sim UNIST
초청발표 TJ2-A-5 11:55-12:25	Global No.1 HBM2E, HBM3의 품질/수율 경쟁력 동시 확보 Look Back 및 차세대 제품에서의 도전 과제 Sung Woo Ma, Jin Hee Lee, and Woong-sun Lee WLP Technology Group, SK hynix